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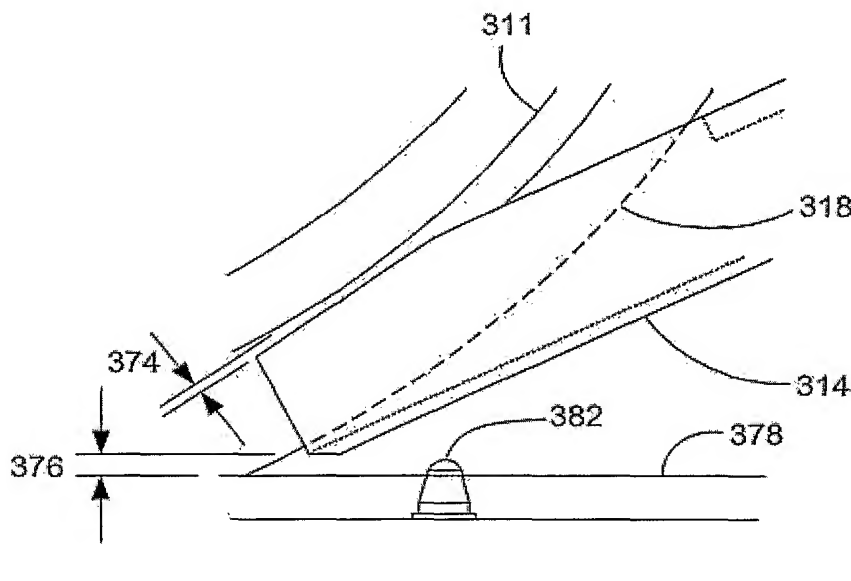
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- (71) Applicants (for all designated States except US): **KONINKLIJKE PHILIPS ELECTRONICS N.V.** [NL/NL]; Groenewoudseweg 1, NL-5621 BA Eindhoven (NL). **TOWA INTERCON TECHNOLOGY INC.** [US/US]; 18255 Sutter Blvd, Morgan Hill, California 95037 (US).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **IN 'T VELD, Frederik, H.** [NL/NL]; c/o Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL). **PRAJUCKAMOL, Atapol** [TH/TH]; c/o Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL). **SAVENIJE, Johannes, H.** [NL/NL]; c/o Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL).
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(54) Title: NOZZLE ASSEMBLY FOR A SAW FOR SEMICONDUCTORS



(57) Abstract: A nozzle assembly (314) for directing flow of fluid across one or more semiconductor device cutting blades (318), comprising: one or more nozzles configured to protrude toward a cutting blade for cutting a semiconductor device; and a channel formed in each of the nozzles, the channel being configured to at least partially surround the cutting blade, so as to simultaneously direct flow of a fluid onto the cutting edge of the cutting blade and onto the sides of the cutting blade.

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